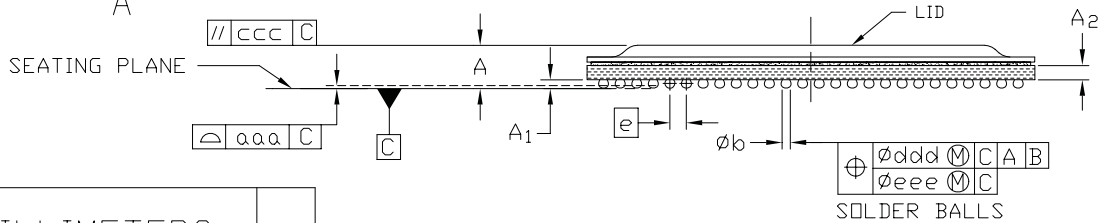
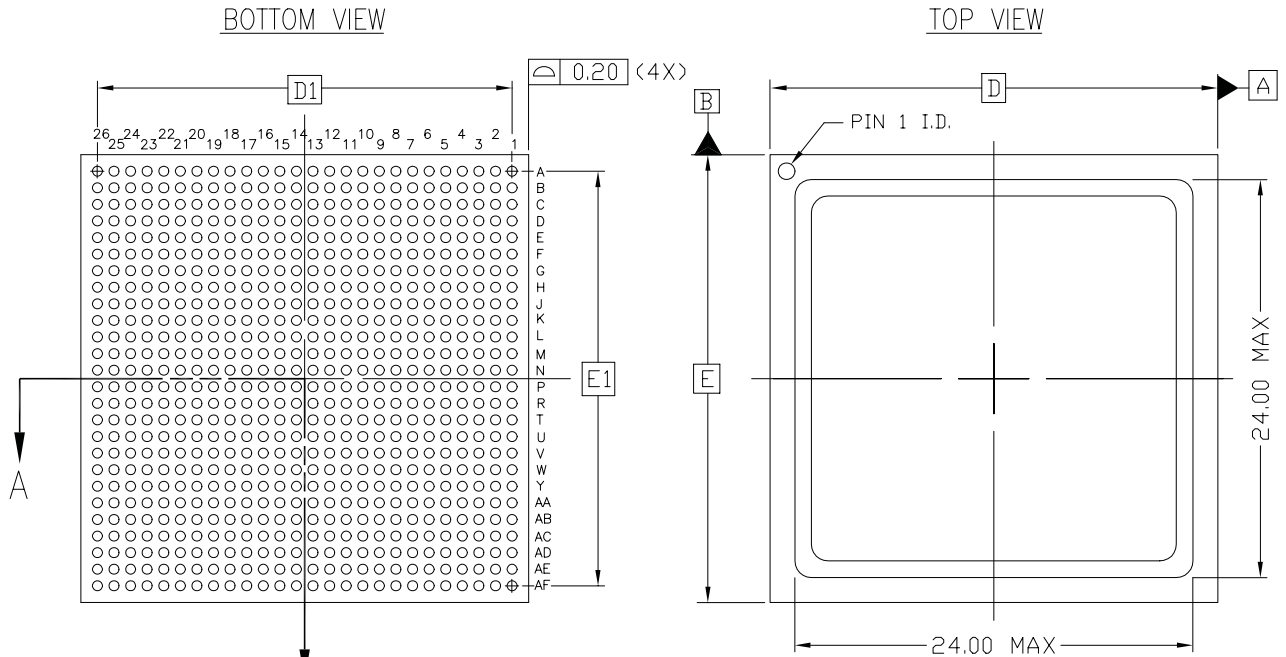
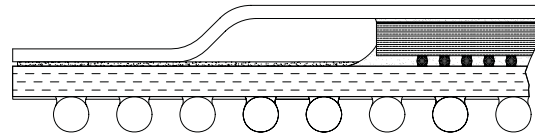


Flip-Chip BGA (FF676) Package



SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	2.35	\approx	3.00	
A ₁	0.40	\approx	0.60	
A ₂	0.65	\approx	1.10	
D/E	27.00 BASIC			
D ₁ /E ₁	25.00 REF			
e	1.00 BASIC			
phi b	0.50	0.60	0.70	
aaa	\approx	\approx	0.20	
ccc	\approx	\approx	0.25	
ddd	\approx	\approx	0.25	
eee	\approx	\approx	0.10	
M	26			2



SECTION A-A
(NOT TO SCALE)

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-AAL-1

676-BALL FLIP-CHIP BGA (FF676)

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
4/10/06	1.0	Initial Xilinx release.
8/27/07	1.1	Corrected symbol typos (D/E, D1/E1).